

BOND SURFACE CONDITIONING SYSTEM FOR IMPROVED BONDABILITY

ABSTRACT

Thick film bond surfaces (8) on a support structure (10), such as a ceramic substrate or an IC package substrate, tend to deform during processing. A personality kit (16) having raised bosses (24) engages with and compresses the bond surfaces, resulting in a flatter, wider bond surface having improved reflectivity. The personality kit (16) is fit within a clamp (30) that can be used as a stand-alone unit or integrated into an existing machine, such as a wire bonder (46).